

<b>PCN Number:</b>	20161215003		<b>PCN Date:</b>	Dec 16 2016	
<b>Title:</b>	Qualification of new Assembly site and Material Set for the LM97937RMER/T				
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services		
<b>Proposed 1<sup>st</sup> Ship Date:</b>	March 16 2017	<b>Estimated Sample Availability:</b>	Provided upon Request		
<b>Change Type:</b>					
<input checked="" type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		
<b>PCN Details</b>					
<b>Description of Change:</b>					
Texas Instruments is pleased to announce the qualification of UTAC as a new Assembly site for the LM97937RMER/T. Construction differences are as follows:					
	<b>What</b>	<b>TI Melaka</b>	<b>UTAC</b>		
	Mount Compound	8001111	<b>SID#PZ0035</b>		
	Mold Compound	8095387	<b>SID#CZ0288</b>		
	Bond Wire, diameter	Au, 1.0 mils	<b>Cu, 0.8 mils</b>		
<b>Reason for Change:</b>					
Continuity of Supply					
<b>Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):</b>					
None					
<b>Anticipated impact on Material Declaration</b>					
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <a href="#">TI ECO website</a> .		
<b>Changes to product identification resulting from this PCN:</b>					
<b>Assembly Site</b>	<b>Assembly Site Origin (22L)</b>	<b>Assembly Country Code (21L)</b>	<b>Assembly City</b>		
TI Melaka	CU6	MYS	Melaka		
<b>UTAC</b>	<b>NSE</b>	<b>THA</b>	<b>Bangkok</b>		
Sample product shipping label (not actual product label)					



MADE IN: Malaysia  
ZDC: 2Q:

MSL '2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:  
ITEM:

LBL: 5A (L)T0:1750



(1P) SN74LS07NSR  
(Q) 2000 (D) 0336  
(31T) LOT: 3959047MLA  
(4W) TKY (1T) 7523483SI2  
(P)  
(2P) REV: (V) 0033317  
(20L) CSO: SHE (21L) CCO: USA  
(22L) ASO: MLA (23L) ACO: MYS

**Topside Device marking (if included):**

Assembly site code for CU6= U

**Assembly site code for NSE = J**

**Product Affected**

LM97937RMER	LM97937RMET
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TI Information  
Selective Disclosure

**Qualification Report**

Qualification of LM97937 product family at UTAC with Cu wirebond  
Approve Date 07-Dec-2016

**Product Attributes**

Attributes	Qual Device: LM97937RME_Cu	QBS Product Reference: LM97937RME	QBS Process Reference: QEVOP2A	QBS Package Reference: ADC14X250	QBS Package Reference: DAC5682ZIRGCR
Assembly Site	UTAC	TIEMAT	A7	UTAC	UTAC
Package Family	QFN	QFN	PLCC	QFN	QFN
Flammability Rating	UL 94 V-0	UL 94 V-0	-	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	MFAB	MFAB	MFAB	MFAB	RFAB
Wafer Process	BICMOS13	BICMOS13	BICMOS13	BICMOS13	C05

- QBS: Qual By Similarity  
- Qual Devices qualified at LEVEL3-260C: LM97937RME\_PCC, LM97937RME\_AU

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LM97937RME_Cu	QBS Product Reference: LM97937RME	QBS Process Reference: QEVOP2A	QBS Package Reference: ADC14X250	QBS Package Reference: DAC5682ZIRGCR
AC	Autoclave 121C	96 Hours	3/231/0	2/77/0	-	-	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	-	Pass	-	Pass	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	3/231/0	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	1/77/0	3/231/0	-
HBM	ESD - HBM	4000 V	-	1/3/0	-	-	-
CDM	ESD - CDM	1500 V	-	1/3/0	-	-	-
HTOL	Life Test, 125C	1000 Hours	-	-	3/231/0	-	-
HTOL	Life Test, 80C	952 Hours	-	1/77/0	-	-	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	3/231/0	-	-	3/231/0	-
LU	Latch-Up	(per JESD78)	-	2/12/0	3/18/0	3/18/0	-
TC	Temperature Cycle, -40/125C	1000 Cycles	-	-	1/77/0	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	1/77/0	-	3/231/0	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	-	-	3/231/0	3/231/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable  
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours  
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours  
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>  
**Green/Pb-free Status:**  
Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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